Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP FF 5930-4Slot Switch(JH179A)
HP FF 5930-4Slot TAA Switch(JH188A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing		0

radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

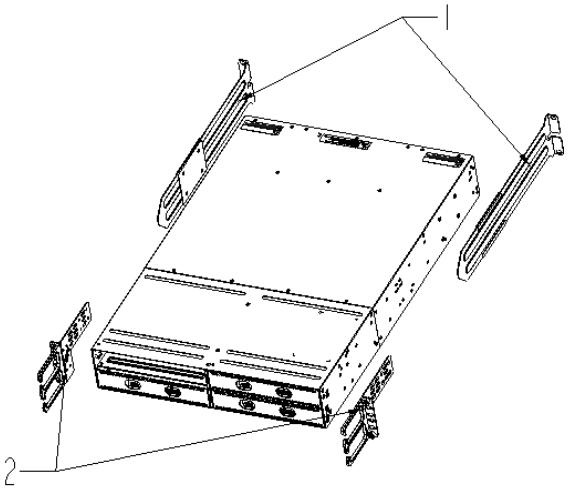
Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 1, and then remove mounting angle 1.
2. Unscrew the screws on mounting angle 2, and then remove mounting angle 2.
3. Remove the power blank panel 3 and the card blank panel 4.
4. Unscrew the screws on top cover 5, and then remove top cover 5.
5. Unscrew the screws on PCB 6, and then remove PCB 6.
6. Unscrew the screws on CPU PCB 7, and then remove CPU PCB 7.
7. Unscrew the screws on flash PCB 8, and then remove flash PCB 8.
8. Unscrew the screws on plate 9, and then remove plate 9.
9. Unscrew the screws on PCB 10, and then remove PCB 10.
10. Unscrew the screws on PCB bracket 11, and then remove PCB bracket 11.
11. Unscrew the screws on plate 12, and then remove plate 12.
12. Unscrew the screws on PCB 13, and then remove PCB 13.
13. Unscrew the screws on bus bar 14, and then remove bus bar 14.
14. Remove all of the labels from the chassis.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



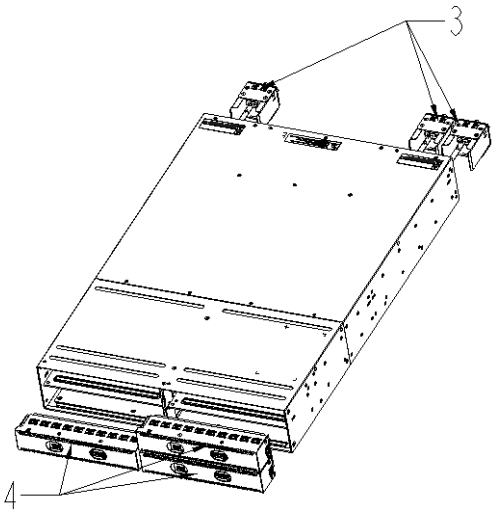


Figure 1Remove mounting angleFigure 2 Remove blankpanel

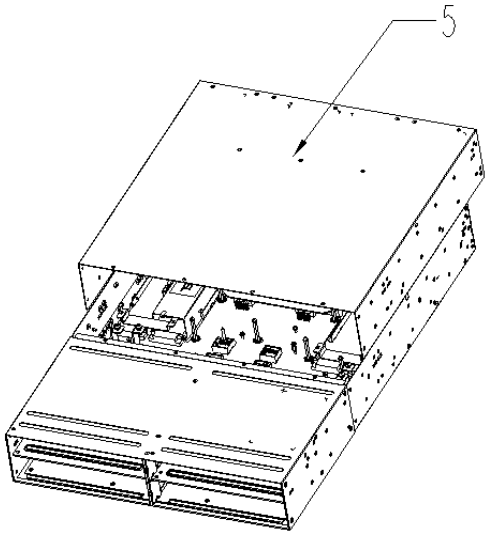


Figure 3Remove top cover

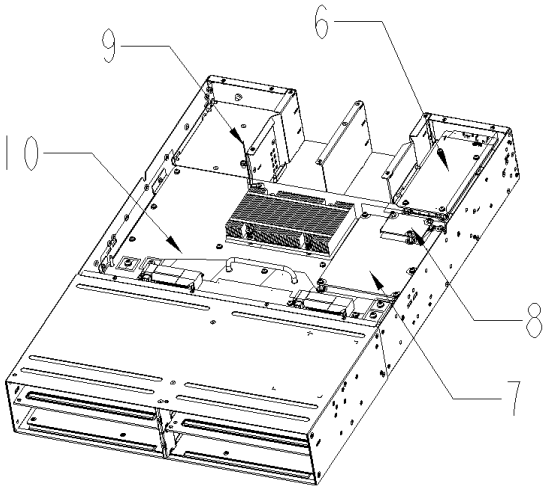


Figure 4Treatments to the product

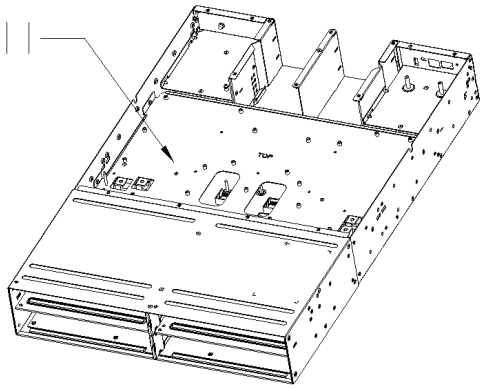


Figure 5Remove PCB bracket

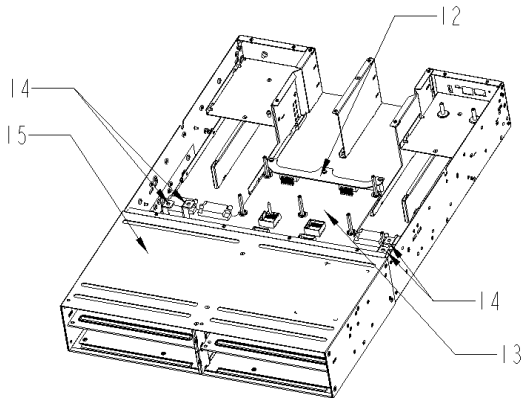


Figure 6Treatments to the product

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	829（2X）	5.6%		Fe recycling
2		Fe	200（2X）	1.3%		Fe recycling
3		Fe	429（3X）	2.9%		Fe recycling
4		Fe	585（3X）	4.0%		Fe recycling
5		Fe	2120	14.4%		Fe recycling
6		Complex	80	0.5%	The surface of PCB is greater	

		PWB			than 10 square centimeters;	
7		Complex PWB	200	1.4%	The surface of PCB is greater than 10 square centimeters;	
8		Complex PWB	10	0.1%	The surface of PCB is greater than 10 square centimeters;	
9		Fe	18	0.1%		Fe recycling
10		Complex PWB	540	3.7%	The surface of PCB is greater than 10 square centimeters;	
11		Fe	800	5.5%		Fe recycling
12		Fe	38	0.3%		Fe recycling
13		Complex PWB	1460	10.0%	The surface of PCB is greater than 10 square centimeters;	
14		Cu	80（4X）	0.5%		Cu recycling
15		Fe	7280	49.6%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2015.02.11	V0	Liu Baoquan	Initial version